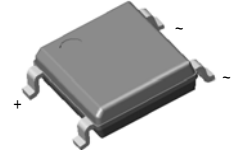
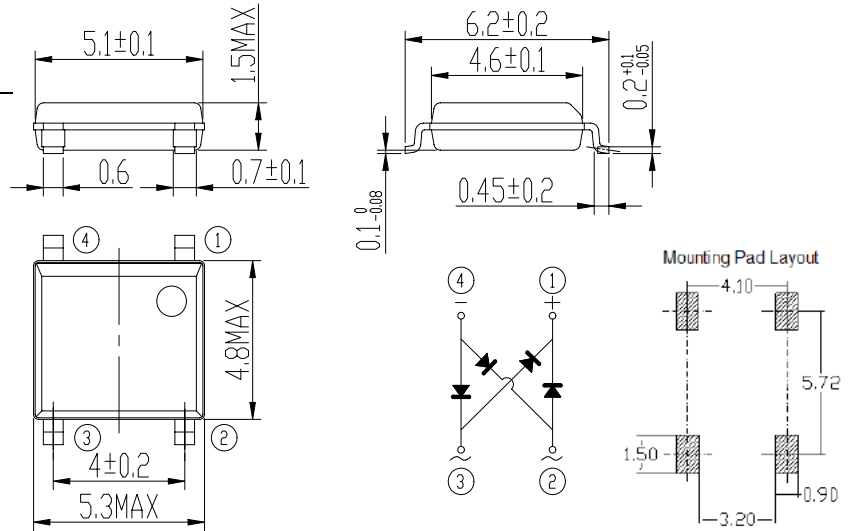


**Features**

Low Profile: Typical height of 1.4mm
Ideal for automated placement
High surge current capability
Solder Dip 260 , 10seconds

**Mechanical Data**

Case:SOPA-4
Epoxy meets UL-94V-0 Flammability rating
Terminals:Matte tin plated Idads, solderable per
J-STD-002B and JESD22-B102D
Polarity:As markde on body

**Maximum Ratings & Electrical Characteristics** Ratings at 25

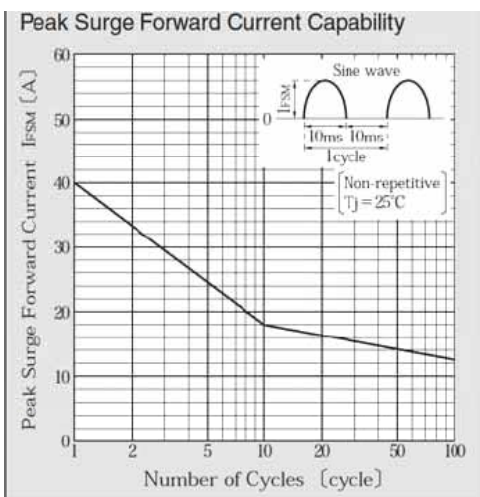
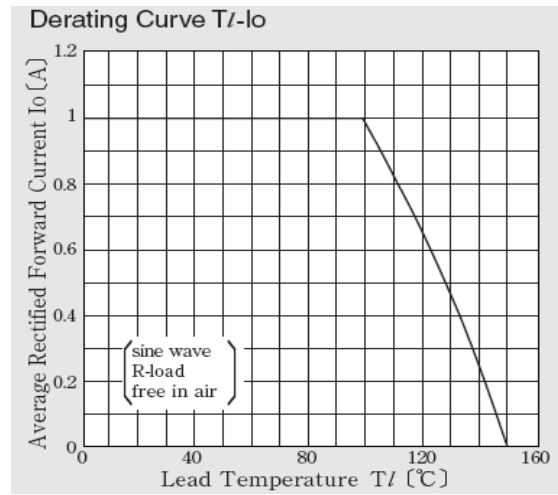
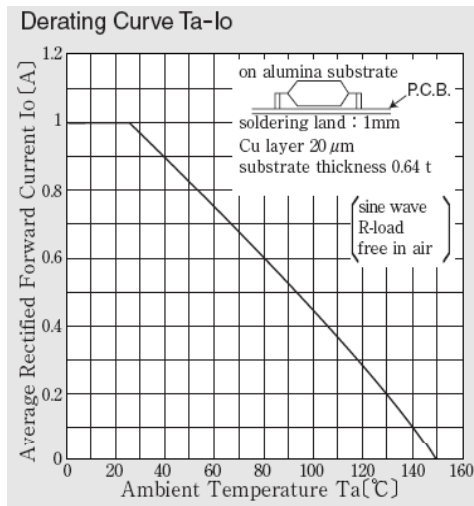
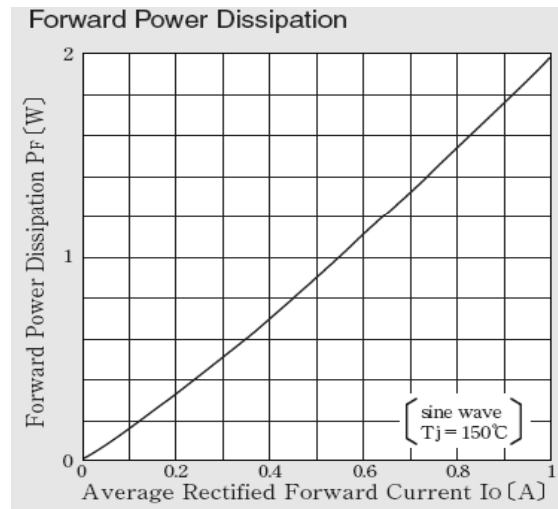
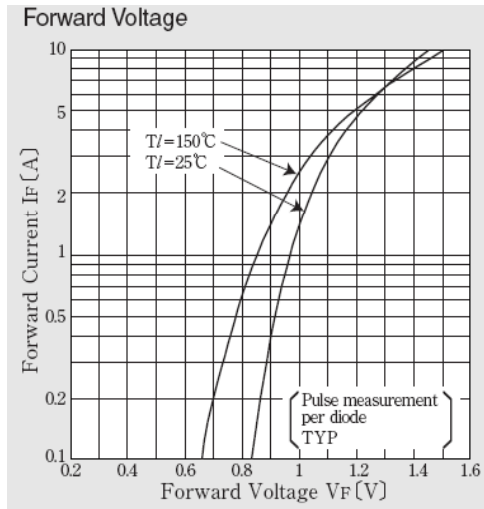
ambient temperature unless otherwise specified.

Parameter	Symbol	LB2SB	LB4SB	LB6SB	LB8SB	LB10SB	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average forward output rectified current on glass-epoxy P.C.B on aluminum substrate	$I_{F(AV)}$	0.8 1.0					A
Peak forward surge current 8.3 ms single sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	40					A
Rating for fusig ($t < 8.3ms$)	I^2t	6.5					A ² sec
Maximum instantaneous forward voltage drop per diode at 1.0A	V_F	1.00					V
Maximum DC reverse current at $T_A=25$ rated DC blocking voltage per leg $T_A=125$	I_R	5 500					μA
Typical thermal resistance per leg (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	80 25					/W
Operating junction temperature range	T_J	-55 to +150					
Storage temperature range	T_{STG}	-55 to +150					

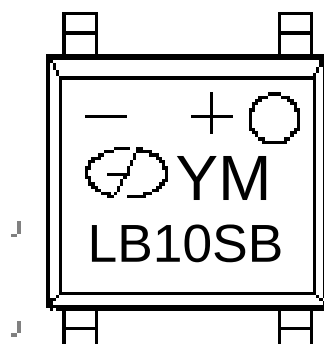
Notes: 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.
2. JEDEC registered values

RATINGS AND CHARACTERISTIC CURVES

($T_A=25^\circ\text{C}$ unless otherwise noted)



Marking



DATE CODE

Year	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020
Code	9	A	B	C	D	E	F	G	H	J	K	0
Month	1	2	3	4	5	6	7	8	9	10	11	12
Code	1	2	3	4	5	6	7	8	9	O	N	D